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**Product
Bulletin**

800-1110

E-SHIELD EC-1110 SINGLE COMPONENT SILVER FILLED ADHESIVE

GENERAL DESCRIPTION

E-SHIELD EC-1110 is a single component, 100 % solids, heat curing electrically conductive epoxy adhesive. This versatile conductive adhesive exhibits excellent mechanical integrity and thermal stability with no chemical corrosion at elevated temperature exposure during wire bonding and soldering.

E-SHIELD EC-1110 exhibits excellent impact and vibration resistance. It is designed for use in the electrical and mechanical bonding of semiconductor, capacitor, and resistor chips in micro and opto-electronic hybrid circuit fabrication.

E-SHIELD EC-1110 is a smooth, soft paste that can be applied by hand application, automatic dispenser, screen, transfer, or stamping technique.

STORAGE AND HANDLING:

Since settling may occur in storage, remix each container prior to use. Refrigeration during storage will minimize filler settling and help maintain viscosity and electrical conductivity. If refrigeration storage is used, to avoid condensation, allow to stabilize to room temperature before opening and using material.

TYPICAL SPECIFICATIONS:

Viscosity:	Soft Creamy Paste
Pot Life, 100 gram mass @ 25°C	N/A
Shelf Life:	Single Component 3 Months 23°F 12 Months -40°F
Silver Content:	70%
Thermal Conductivity, BTU/hr/ft ² /°F/in.:	16.2
Volume Resistivity, OHM-CM:	7x10 ⁻³
Operating Temp. Range, °C:	-55 to +170
Cure Schedule	2 Hours at 120°C 60 Minutes at 150°C 30 Minutes at 160°C

INSTRUCTIONS FOR USE:

- 1) All surfaces to be bonded or coated should be completely cleaned and grease free.
- 2) Mix thoroughly prior to removing from container.
- 3) Cure according to one of the following cure Schedules:

2 Hours at 120°C
60 Minutes at 150°C
30 Minutes at 160°C

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